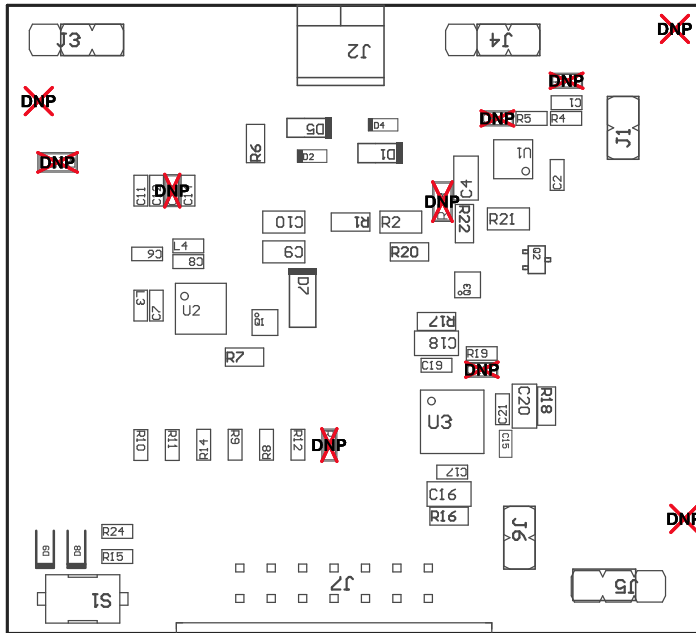


Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22 ■ This Assembly Note will show in the PcbDoc and associated outputs

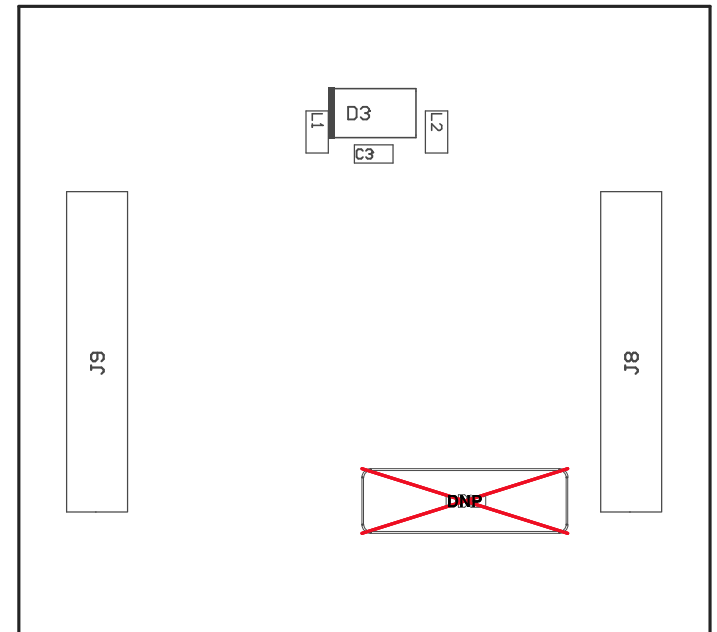
Z23 ■ This Assembly Note will show in the PcbDoc and associated outputs

Z24 ■ This Assembly Note will show in the PcbDoc and associated outputs



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00648	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00648		
PLOT NAME = Top Assembly Drawing	GENERATED : 9/16/2015 1:24:55 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00648	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00648		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/16/2015	1:24:56 PM	TEXAS INSTRUMENTS

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